

**PATENT ASSIGNMENT**

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|                       |                |
|-----------------------|----------------|
| SUBMISSION TYPE:      | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT     |
| EFFECTIVE DATE:       | 09/14/2007     |

**CONVEYING PARTY DATA**

| Name           | Execution Date |
|----------------|----------------|
| Tomohiro UNO   | 09/11/2007     |
| Keiichi KIMURA | 09/11/2007     |
| Takashi YAMADA | 09/14/2007     |

**RECEIVING PARTY DATA**

|                 |                                   |
|-----------------|-----------------------------------|
| Name:           | NIPPON STEEL MATERIALS CO., LTD.  |
| Street Address: | 6-3, Otemachi 2-chome, Chiyoda-ku |
| City:           | Tokyo                             |
| State/Country:  | JAPAN                             |
| Postal Code:    | 100-8071                          |

|                 |                                    |
|-----------------|------------------------------------|
| Name:           | NIPPON MICROMETAL CORPORATION      |
| Street Address: | 158-1 Oaza Sayamagahara, Iruma-shi |
| City:           | Saitama                            |
| State/Country:  | JAPAN                              |
| Postal Code:    | 358-0032                           |

**PROPERTY NUMBERS Total: 1**

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 11848403 |

**CORRESPONDENCE DATA**

Fax Number: (212)527-7701  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
 Phone: (212) 527-7783  
 Email: kma@darbylaw.com  
 Correspondent Name: Joseph R. Robinson

OP \$40.00 11848403

Address Line 1: P.O. Box 770, Church Street Station  
Address Line 4: New York, NEW YORK 10008-0770

ATTORNEY DOCKET NUMBER: 09864/0207887-US0

NAME OF SUBMITTER: Kenneth Ma

Total Attachments: 2  
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ASSIGNMENT

For value received, I/we Tomohiro UNO, Keiichi KIMURA and  
Takashi YAMADA  
residing respectively at Tokyo, Japan; Tokyo, Japan; Saitama, Japan

hereby sell, assign, and transfer to NIPPON STEEL MATERIALS CO., LTD.;  
NIPPON MICROMETAL CORPORATION  
corporations existing under the laws of Japan  
located at 6-3, Otemachi 2-chome, Chiyoda-ku, Tokyo 1008071, Japan; 158-1, Oaza  
Sayamagahara, Iruma-shi, Saitama 3580032, Japan

and its successors, assigns, and legal representatives, the entire right, title, and interest for  
all countries including the United States of America, in and to certain inventions relating to  
COPPER ALLOY BONDING WIRE FOR SEMICONDUCTOR DEVICE;  
SN 11/848,403 filed on August 31, 2007

described in an application for Letters Patent of the United States, executed by me/us on this  
date, and all patents which may be granted therefor, and all divisions, reissues, continuations  
and extensions thereof, and authorize and request the Commissioner of Patents and  
Trademarks to issue all patents on said improvements or resulting therefrom to said  
Company as assignee of the entire interest, and covenant that I/we have full right so to do,  
and agree that I/we will communicate to said Company or its representatives any facts  
known to me/us respecting said improvements and testify in any legal proceedings, sign all  
lawful papers, execute all divisional, continuing and reissue applications, make all rightful  
oaths and generally do everything possible to aid said Company, its successors, assigns, and  
nominees, to obtain and enforce proper protection for said invention in the United States.

Signature Tomohiro UNO  
Tomohiro UNO

Date September 11, 2007

Signature Keiichi KIMURA  
Keiichi KIMURA

Date September 11, 2007

Signature \_\_\_\_\_  
Takashi YAMADA

Date \_\_\_\_\_

Signature \_\_\_\_\_

Date \_\_\_\_\_

Signature \_\_\_\_\_

Date \_\_\_\_\_

Signature \_\_\_\_\_

Date \_\_\_\_\_

ASSIGNMENT

For value received, I/we Tomohiro UNO, Keiichi KIMURA and Takashi YAMADA residing respectively at Tokyo, Japan; Tokyo, Japan; Saitama, Japan

hereby sell, assign, and transfer to NIPPON STEEL MATERIALS CO., LTD.;  
NIPPON MICROMETAL CORPORATION  
corporations existing under the laws of Japan  
located at 6-3, Otemachi 2-chome, Chiyoda-ku, Tokyo 1008071, Japan; 158-1, Oaza Sayamagahara, Iruma-shi, Saitama 3580032, Japan

and its successors, assigns, and legal representatives, the entire right, title, and interest for all countries including the United States of America, in and to certain inventions relating to COPPER ALLOY BONDING WIRE FOR SEMICONDUCTOR DEVICE;  
SN 11/848,403 filed on August 31, 2007

described in an application for Letters Patent of the United States, executed by me/us on this date, and all patents which may be granted therefor, and all divisions, reissues, continuations and extensions thereof, and authorize and request the Commissioner of Patents and Trademarks to issue all patents on said improvements or resulting therefrom to said Company as assignee of the entire interest, and covenant that I/we have full right so to do, and agree that I/we will communicate to said Company or its representatives any facts known to me/us respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees, to obtain and enforce proper protection for said invention in the United States.

Signature \_\_\_\_\_ Date \_\_\_\_\_  
Tomohiro UNO

Signature \_\_\_\_\_ Date \_\_\_\_\_  
Keiichi KIMURA

Signature Takashi Yamada Date September 14, 2007  
Takashi YAMADA

Signature \_\_\_\_\_ Date \_\_\_\_\_

Signature \_\_\_\_\_ Date \_\_\_\_\_

Signature \_\_\_\_\_ Date \_\_\_\_\_